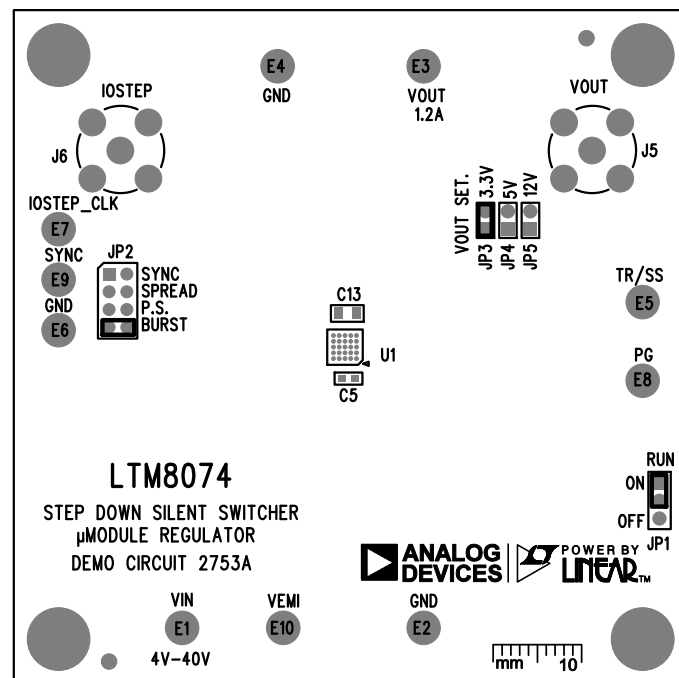


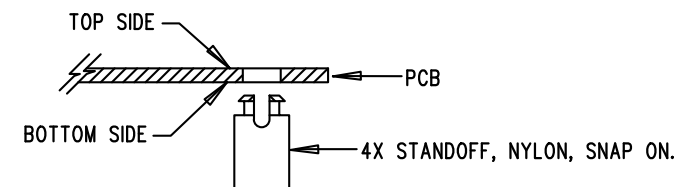
REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	4	PRODUCTION	SY	04-25-18

TOP VIEW SHOWN



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPROVALS		 ANALOG DEVICES		 POWER BY LINEAR™		www.analog.com	
PCB DES.	LT	FOR ADI CUSTOMER USE ONLY					
APP ENG.	SY	TITLE: TOP ASSEMBLY DRAWING STEP DOWN SILENT SWITCHER μMODULE REGULATOR					
		SIZE N/A	IC NO. LTM8074EY DEMO CIRCUIT 2753A				REV. 4
SCALE = NONE		FILENAME: DC2753A-4.PCB				SHT 1 OF 2	